

QP#10511: AD5748\_AD5750\_AD5750-1\_AD5750-2 Die Rev and Package Qualification

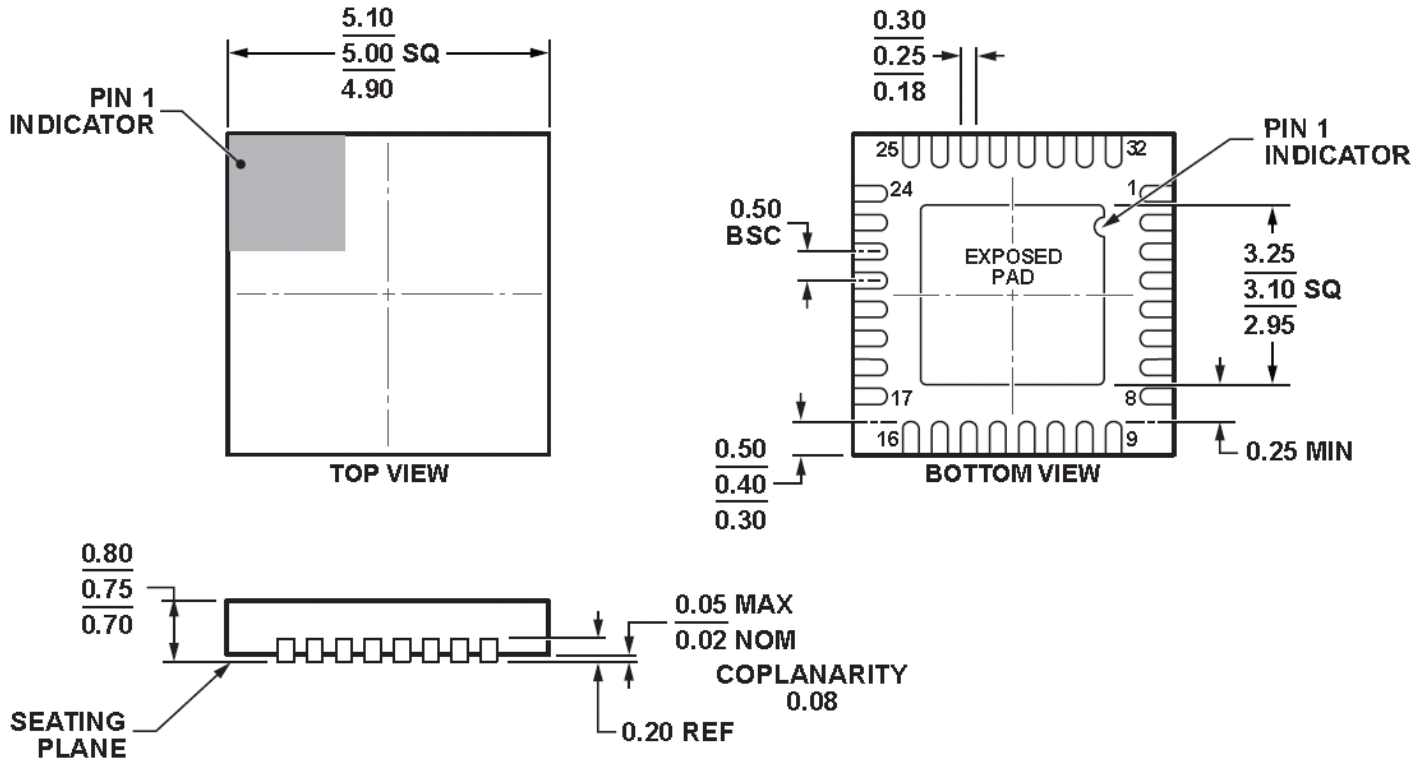
QUALIFICATION PLAN# 10511 /INCOMPLETE			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
High Temperature Operating Life (HTOL)*	JEDEC <i>JESD22-A108</i>	7 x 45 3 x 77	Pass Pass
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	3 x 77 3 x 77	Pass Expected in May
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77 3 x 77	Pass Expected in May
Autoclave (AC)*	JEDEC <i>JESD22-A102</i>	3 x 77 3 x 77	Pass Expected in May
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	1 x 45 1 x 45	Pass Expected in April
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	1 x 30	Pass
Latch-Up	JEDEC <i>JESD78</i>	3	Pass
Electrostatic Discharge <i>Human Body Model</i>	ESDA/JEDEC <i>JS-001</i>	3/voltage	Pass __3KV
Electrostatic Discharge <i>Field-Induced Charged Device Model</i>	JEDEC <i>JESD22-C101</i>	3/voltage	Pass _1.25KV

\*Preconditioned per JEDEC/IPC J-STD-020



32-Lead Lead Frame Chip Scale Package [LFCSP\_WQ]  
5 x 5 mm Body, Very Very Thin Quad  
(CP-32-7)

Dimensions shown in millimeters



COMPLIANT TO JEDEC STANDARDS MO-220-WHHD.